

ABSTRACT

In a wafer dicing/die bonding sheet comprising a
5 backing member, an adhesive layer, and a protective member,
the adhesive layer is made of an adhesive composition
comprising a phenolic hydroxyl radical-bearing polyimide
resin, an epoxy resin, and an epoxy resin curing agent, the
ratio of the total weight of the epoxy resin and the epoxy
10 resin curing agent to the weight of the polyimide resin being
from 0.1:1 to 3:1. Due to heat resistance, improved adhesive
properties and a low modulus of elasticity, the wafer
dicing/die bonding sheet is effective for reducing the
warpage of a chip after die bonding.